

# OCtoPus 1.8iP

# SERVER BASED ON OCP PRINCIPLES

21-inch - 20penU - 2 CPUs and 8 GPUs - Front IO

# **Key Features**



21-inch - 2OU / 2 CPUs / 8 GPUs - Front IO



Dual 3rd Generation Intel® Xeon® Scalable Processors Socket P+



16x DDR4 @ 3200MHz



8x PCle 4.0 x8 + 2x PCle 4.0 HL LP



OCP technology 12V DC



IPMI / iKVM with ASPEED® AST2600



**Immersion Cooling** 





#### **3rd Gen Intel Xeon Scalable Processors**

The OCtoPus 1.8iP has been built for those who need a flexible and efficient solution. The 3rd Gen Xeon Scalable processors offer a balanced architecture with built-in acceleration and advanced security capabilities.

### Scale out and scale up

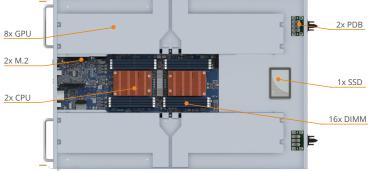
Scaling is critical to HPC applications. AMD EPYC<sup>™</sup> 7xx3 Series Processors provide high bandwidth between nodes with support for PCle Gen4 enabled network devices and accelerators. AMD 3rd Generation processors help HPC workloads scale across on-premise clusters and bring HPC-level performance to the cloud for time-sensitive projects.

## Certi ied by the Solar Impulse Foundation

To address sustainability challenges while enabling economic growth Bertrand Piccard, serial explorer, initiator and visionary behind Solar Impulse has iden-ti ied with its Foundation, 1000+ clean and pro itable solutions including the OCtoPus server solution since October 2021.

Front I/O view







# **SPECIFICIATIONS**

System	Model	OCtoPus 1.8EE
	Form Factor	21-inch 2OpenU
	Nodes	2 CPUs
	Dimension	845 x 537 x 86mm 33"x 21" x 3.3"
Motherboard	СРИ	2x Socket P+ (LGA 4189) 3rd Generation Intel® Xeon® Scalable Processors
	Chipset	Intel® C621A Express Chipset
	GPU	Up to 8x Dual-slot Nvidia® GeForce, Tesla, Quadro or AMD Vega, Vega Pro cards Maximum limitation of GPU card: 285 x 111.5 x 39.5mm (LxWxH)
	Expansion slots	8x PCIe x8 (4x Gen4 x16 bus) for GPUs 2x PCIe x16 (Gen4 x16 bus) Half-length low-profile slot
	вмс	Aspeed® AST2600
Memory	Total Slots	16 (8-channel per CPU, 8 DIMM per CPU)
	Capacity per DIMM	Maximum up to 128GB (with RDIMM / LRDIMM modules) Maximum up to 256GB (with 3DS RDIMM / LRDIMM modules)
	Memory Speed	Up to 3200 MHz
Network		1x RJ45 for dedicated management (IPMI) 2 x 10Gb/s BASE-T LAN ports (Intel® X710-AT2)
Front I/O	Ports	2x USB 3.0 1x VGA 2x RJ45 (1GbE) 1x RJ45 dedicated IPMI (MLAN)
	Switch/LED	1x Power button with LED 1x ID button with LED 1x Reset button 1x NMI button 1x System status LED
Management Solution	Out of Band Remote Management	BMC Remote control based on Aspeed® AST2600 remote management controller (Power Control Configuration, Chassis Identify, Boot Option, iKVM, BMC Account Configuration)
Power Supply	Туре	OCP Principles: Power Supplies are mutualized at the back of the rack